

**METHOD OF SELF-ANNEALING CONDUCTIVE LINES  
THAT SEPARATES GRAIN SIZE EFFECTS  
FROM ALLOY MOBILITY**

**ABSTRACT OF THE DISCLOSURE**

5           A method of forming a conductive structure such as a  
copper conductive structure, line, or via is optimized for large grain  
growth and distribution of alloy elements. The alloy elements can reduce  
electromigration problems associated with the conductive structure. The  
conductive structure is self-annealed or first annealed in a low  
10   temperature process over a longer period of time. Another anneal is  
utilized to distribute alloy elements.